

polyEpoxy resin impregnated glass fabric laminate board - has intermediate layer contg. acicular inorganic filler, useful for printed circuit boards

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Patent Details:

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Abstract (Basic): JP 1222950 A

A laminated board is composed of surface layers made of epoxy resin-glass woven fabric, and an intermediate layer made of epoxy resin and a non-woven fabric contg. a needle-shape inorganic filler in an amt. of 10-250 wt.% based on the resin in the intermediate layer.

Pref., the needle-shape inorganic filler has a needle dia. of 2-20 microns, a needle length of 3-100 microns, and an aspecto ratio of 3-15; the needle-shape inorganic filler is woolastnite.

USE/ADVANTAGE - The laminate has improved mouldability, i.e. the thickness redn. at the edges of the laminate and the void formation are prevented. The heat resistance is high.

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Title Terms: POLYEPOXIDE; RESIN; IMPREGNATE; GLASS; FABRIC; LAMINATE; BOARD ; INTERMEDIATE; LAYER; CONTAIN; ACICULAR; INORGANIC; FILL; USEFUL; PRINT; CIRCUIT; BOARD

Derwent Class: A21; A85; L03; P73

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